

Thermally Settable Pad

RoHS-compliance with halogen free & lead free process

Thermal Settable Pad, TSP

TSP is a kind of thermal interface material that combines advantage with low thermal resistance, electrical isolation, and thermal settable properties. Based on the epoxy resin and specific ceramic filler, this product can be used as adhesive material for the interface assembly especially for electric component manufacturing, such as LED bulb, PCB, Heat sink and etc.

Comparing with tradition thermal interface material, TSP provides more design freedoms particularly in the thin shape structure, high reliability, and high thermal conductivity applications.

Features

- Excellent thermal conductivity
- High breakdown voltage
- Easy process
- Thermal curing at elevated temperature
- Customized structure available

Applications

- Power electronics
- Automotivee
- High brightness LED module
- Printed Circuit Board

Product Description

TSP is a kind of electrically insulating and thermal conductive sheet.

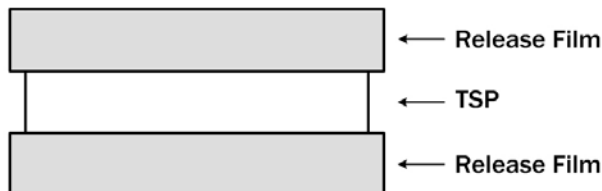


Figure 1. Substrate structure of TSP

Table 1. Standard Specification

Characteristic	Material	Type
Release Film Thickness	PET	50μm
TSP Thickness	Epoxy filler	160, 200μm

* If there's any specific requirement about the substrate structure, please contact us.

Thermally Settable Pad

RoHS-compliance with halogen free & lead free process

Part Number System of TSP

